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**PATENT**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Norio FUKASAWA et al.

Serial No.: 09/029,608

Filed: May 15, 1998

For: METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,  
SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE

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**SECOND SUPPLEMENTAL PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

June 4, 1999

Sir:

Further to the Supplemental Preliminary Amendment filed on February 26, 1999, please  
amend the above-identified application as follows:

**IN THE CLAIMS:**

Please cancel claims 13-17 without prejudice or disclaimer and add new claims 103-108  
as follows:

--103. A mold for fabricating a semiconductor device comprising:

a first mold; and

a second mold which is located so as to face the first mold,

the second mold including a first half body having a shape corresponding to a shape of a  
substrate, and a second half body which is provided so as to surround the first half body and can  
be elevated with respect to the first half body,

the first and second half bodies cooperating with each other so that a cavity to be filled